TO.: Reference Sheet NO.: A250201



# **APPROVAL SHEET**

# **MULTILAYER CERAMIC CAPACITOR**

**Commercial Grade** 

(Thin Layer Large-Capacitance Type)



Address: 227,GYEONGGIDONG-RO, NAMSA-EUP, CHEOIN-GU, YONGIN-SI, GYEONGGI-DO, KOREA

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Home page: www.samwha.com

# \* Notice

This sheet is for reference only and is subject to change or be discontinued without notice. Please contact our sales representatives for detailed information.

	< SPECIFICATION SUMMARY >									
SAMWHA Part no.			CS3216X5R226K250NRI							
Туре		Gene	ral / Thin Layer Large-Capacitance							
Items	Specification	Unit	Test Conditions							
Capacitance	22.0	μF	Testing Frequency: 120 ± 24Hz							
Capacitance Tolerance	± 10	%	Testing Voltage : $0.5 \pm 0.1 \text{Vrms}$ Should be measured at $25^{\circ}\text{C}$							
Dissipation Factor	Max. 12.5	%								
Insulation Resistance	More than 2.27	MΩ	Should be measured with a DC voltage not exceeding rated voltage at 25°C for 2 minutes of charging.							
	3.20 ± 0.30	L (mm)	Capacitance Tolerance Codepage 4/14							
Chip Size	1.60 ± 0.20	W (mm)	Chip sizepage 5/14 Characteristics & Test Methodpage 6/14~8/14							
	1.60 ± 0.20	T (mm)								

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PART NO.		SAMWHA SPEC.	CS3216X5R226K250NRI
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NO	REASON	CONTENTS	DATE OF APPROVAL	CHECKED	REMARKS
1	Initial written	full document	96. 03. 27		
2	Re-revision of approval document	full document	25. 02. 01		

# **General Description**

### 1. General Article

Application Range

These specifications refer to the "Multilayer Ceramic Capacitors" mainly used in various every products such as home appliances, audio/visual equipment, communication devices, and Etc.

\*Caution: Industrial equipment / For the high reliability equipment / LED equipment / Etc.

Please contact sales representatives or product engineers before using the products.

(For details, please referenece "Note" page)

### 2. General Code

(1) Type Designation

<u>cs</u>	<u>3216</u>	<u> X5R</u>	<u>226</u>	<u>K</u>	<u>250</u>	<u>N</u>	<u>R</u>	Ī
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- 1) Multilayer Ceramic Capacitor (Commercial Grade)
- 2) Size Code: This is expressed in tens of a millimeter.

The first two digits are the length, The last two digits are width.

3) Temperautre Coefficient Code

Classification			Capacitance Tolerance
Class II	X5R	-55 to +85°C	± 15 %

# 4) Capacitance Tolerance Code

The nominal Capacitance Value in pF is expressed by three digit numbers.

The first two digits represents significant figures and the last digit denotes the number of zero

ex) 104 = 100000 pF / R denotes decimal / 8R2 = 8.2 pF

### 5) Capacitance Tolerance Code

Code	Tolerance				
В	± 0.1 pF				
С	± 0.25 pF				
D	± 0.5 pF				
F	± 1.0 %				

Code	Code
G	± 2.0 %
J	± 5 %
K	± 10 %
М	± 20 %

### 6) Voltage Code

Code	2R5	040	6R3	100	160	250	350	500	101	201	251	501	631	102	202	302
Rate	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC
Voltage	2.5V	4V	6.3V	10V	16V	25V	35V	50V	100V	200V	250V	500V	630V	1KV	2KV	3KV

### 7) Termination Code

N: Nickel-Tin Plate

A : Nickel-Tin Plate  $\rightarrow$  Soft Termination Type

### 8) Packing Code

R: 7" Reel Type, L: 13" Reel Type, B: Bulk Type

# **General Description**

9) Thickness option

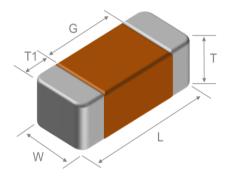
Thickne	Codo		
t	Code		
1.60	0.20	Blank	

# 3. Temperature Characteristics

See Page 8 (Specifications and Test Methods: No.13)

### 4. Constructions and Dimensions

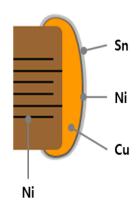
1) Dimensions



(Unit: mm)

			Dimension								
Size Code	EIA Code	Ler	ngth	Wi	dth	T1(min.)	G(min.)				
		L	Tol(±)	W	Tol(±)	1 1(111111.)					
3216	1206	3.20	0.30	1.60	0.20	0.30	1.20				

# 2) Construction of Termination



Spec	cifications	and Tes	t Methods (Thin Layer Large-Capacitance Ty	/pe	)			(IEC-60	384 Qualifi	ed)
No.	Test	Item	Specification			Test M	lethods and	d Conditio	ons	
1	Operating T Rai		-55 ~ 85℃							
2	Insulation I	Resistance	50 Ω.F min	С	harging Time	oplied Voltage Rated voltage narging Time 2min. narge/Discharge Current 50mA max.				
3	Voltag	e proof	No defects or abnormalities	A	pplied Voltag pplied Time harge/Discha		1	250% to 5sec. 0mA max.		
4	Capac	itance	within the specified tolerance		leasurement pplied Voltag			5℃ nown in the t	table	
					Capacita C≦10 <i>i</i>		Frequency		Voltage 0.5~1.0Vrms	
5	Dissipation Factor		12.5% max *3216 Size 100μF : 15% max		C>10µ nitial Measure	ment	120 ± 24Hz 0.5 ± 0.1Vrms  Perform the initial measurement according to Note1 for Class II  Take it out and set it for 24±2 hou		ss II	
6	6 Solderability		95% of the terminations is to be soldered evenly and continuously.	S:	Solder Solder temperature Immersion time Pre-Heating		24 3 :	96.5Sn-3Ag-0.5Cu 245±5°C 3 ± 0.1sec. 80~120°C for 10~30sec.		
		Appearance	No defects which may affect performance	Pi (3	reheat Tempo reheat Time 3225,4520,45	32 Size)	120 to 150°C 1min. 100 to 120°C (Step1) 170 to 200°C (Step2) 1min. 260±5°C			
		Capacitance Change	Within ±7.5%	Pi Si	reheat Temporeheat Time oldering Tem	p				
7	Resistance to Soldering Heat	Dissipation Factor	Within ±12.5% *3216 Size 100μF : 15% max		nmersion Tim		10 Pe	)±0.5 sec. erform the in	iitial measure Note1 for Clas	
		I.R	50 Ω.F min	М	Measurement after test			Let sit at room temperature for 24±2 hours, then measure		
		Appearance	No defects which may affect performance		eat treatment	ts		nown in the t	table	
		Capacitance Change	Within ±7.5%		Step	Min.	2	Max.	4	
8	Rapid change of temperature	Dissipation Factor	12.5% max *3216 Size 100μF : 15% max		Temp (℃) Time (min)	Operating temp. +0, -3 30 ± 3	Room Temp	Operating temp. +3, -0 30 ± 3	Room Temp 2 to 3	
		I.R	50 Ω.F min		nitial measure		Perform the initial measurement according to Note1 for Class II Perform the final measurement according to Note2			ss II

Spec	cifications	and Tes	t Methods (Thin Layer Large-Capacitance Typ	De) (IEC-60384 Qualified)		
No.	Test	Item	Specification	Test Meth	ods and Conditions	
		Appearance	No defects which may affect performance	Testing Time Applied Voltage	1000+48/-0 hrs Rated Voltage x100%	
		Capacitance Change	Within ±12.5%	Temperature (C0G,X7R) Temperature (X5R, Y5V)	125±3°C 85±3°C	
9	Endurance	Dissipation Factor	Within ±20% *3216 Size 100μF : 30% max	Charge/discharge current Initial measurement	50mA max.  Perform the initial measurement according to Note1 for Class II	
		I.R	12.5Ω.F min	Measurement after test	Perform the final measurement according to Note2	
			Support Solder Chip Printed circuit board before testing  45±2  1.60 ± 0.20 m or 0.80 ± 0.10 m  Speed: 1.0 mm/s	Substrate material Thickness	Glass Epoxy Board  1.6mm  0.8mm (0603/1005size)	
10	Substrate bending test		Printed circuit board under test  Displacement  No cracking or marking defects shall occur	Bending limit Pressurizing speed Holding time	1mm 1mm/sec. 5±1sec.	
		Capacitance Change	Within ±10%	After soldering and then let sit for 2	24±2hr at room temperature	
		Capacitance	No defects which may affect performance  Whin the specified tolerance	Type of Vibration Vibration Time	From 10Hz to 55Hz then 10Hz again 1min.	
11	Vibration	Change  Dissipation Factor	12.5% max *3216 Size 100μF : 15% max	Total Amplitude Vibration directions and time	1.5mm This motion shall be applied for a period of 2 hours in each 3 mutually perpendicular directions (total is 6hours)	
		Appearance	No defects which may affect performance	Applied Voltage Temperature Humidity	Rated voltage 40±2°C 90 to 95%RH	
	Accelerated	Capacitance Change	Within ±12.5%	Time Charge/Discharge Current Initial measurement	500+24/-0 hrs 50mA max.  Perform the initial measurement according	
12	damp heat, steady state	Dissipation Factor	Within ±20% *3216 Size 100 <i>μ</i> F : 30% max	Measurement after test	to Note1 for Class II  Perform the final measurement according to Note2	
		I.R	12.5Ω.F min			

Spec	cifications and Tes	t Method	ds (Thin Layer	pe) (IEC-60384 Qualified)		
No.	Test Item	Specification				Test Methods and Conditions
	Temperature characteristic of capacitance	Char.	Temp. Range	Reference Temp.	Cap. Change	
		X5R	-55 to +85°C	25℃	Within ±15%	The capacitance change should be measured after 5 min at each
		X6S	-55 to +105°C	25℃	Within ±22%	specified temperature stage.
13		X7R	-55 to +125°C	25℃	Within ±15%	The ranges of capacitance change compared with the 25 ℃ value over
	,	X7S	-55 to +125°C	25℃	Within ±22%	the temperature ranges shown in the table should be within the specified
		X7T	-55 to +125°C	25℃	Within +22/-33%	ranges.
		Y5V	-30 to +85°C	25℃	Within +22/-82%	
		X8R	-55 to +150°C	<b>25</b> ℃	Within ±15%	
		X8L	-55 to +150°C	25℃	Within +15/-40%	

<sup>\*</sup>Note1. Initial Measurement for Class II

Perform a heat treatment at 150+0,-10°C for one hour and then let sit for 24±2 hours at room temperature, then measure

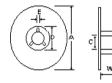
Perform a heat treatment at 150+0,-10°C for one hour and then let sit for 24±2 hours at room temperature, then measure.

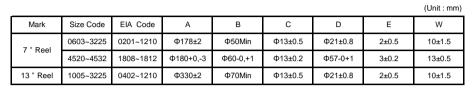
<sup>\*</sup>Note2. Measurement after test Class II

<sup>&</sup>quot;Following the International standards, the title of each test item is subject to change."

# **Packing**

- (1) Bulk Packing
  - 1 1000 pcs per polybag
  - ② 5 polybags per inner box
  - 3 10 inner boxes per out box
- (2) Reel Packing
  - ① 8~10 Reels per inner box
  - 2 6 inner boxes per out box
- (3) Reel Dimensions

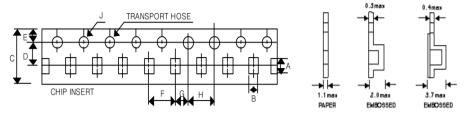




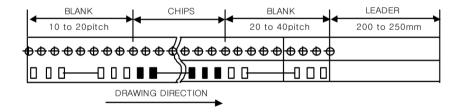
Size Code	EIA Code	7"	13"	
Size Code	EIA Code	Quantity (pcs) / Reel	Quantity (pcs) / Ree	
CS0603	CC0201	15,000	-	
CS1005	CC0402	10,000	50,000	
CS1608	CC0603	4,000	15,000	
CS2012	CC0805	3,000 ~ 4,000	8,000 ~ 15,000	
CS3216	CC1206	2,000 ~ 4,000	6,000 ~ 10,000	
CS3225	CC1210	1,000 ~ 3,000	4,000 ~ 10,000	
CS4520	CC1808	1,500 ~ 3,000	-	
CS4532	CC1812	500 ~ 1,000	1,500 ~ 5,000	

# Packing

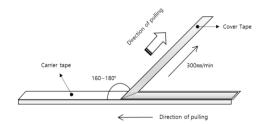
# (5) Tape Dimensions



Size Code	EIA Code	Size	Thickness	А	В	С	D	Е	F	G	Н	J
CS0603	CC0201	0603	all	0.7±0.02	0.4±0.02	8±0.1	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1005	CC0402	1005	all	1.12±0.03	0.62±0.03	8±0.1	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1005	CC0402	1005	all	1.12±0.03	0.58±0.03	8±0.1	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1005	CC0402	1005	all	1.16±0.03	0.66±0.03	8±0.05	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1608	CC0603	1608	A, B	1.8±0.05	0.95±0.05	8±0.1	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1608	CC0603	1608	A, B	1.78±0.05	0.92±0.05	8±0.1	3.5±0.05	1.75±0.05	2±0.05	2±0.05	4±0.1	1.55±0.03
CS1608	CC0603	1608	В	1.9±0.05	1.1±0.05	8±0.2	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.1	1.5+0.1
CS1608	CC0603	1608	В	1.9±0.05	1.1±0.05	8±0.1	3.5±0.05	1.75±0.05	4±0.1	2±0.05	4±0.1	1.55±0.03
CS2012	CC0805	2012	Е	2.25±0.1	1.35±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS2012	CC0805	2012	Е	2.4±0.1	1.6±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS2012	CC0805	2012	Е	2.25±0.1	1.35±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.1	1.5+0.1
CS2012	CC0805	2012	Е	2.25±0.05	1.53±0.08	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.1	1.5+0.1
CS2012	CC0805	2012	А	2.3±0.05	1.55±0.05	8±0.1	3.5±0.05	1.75±0.05	4±0.1	2±0.05	4±0.1	1.55±0.03
CS2012	CC0805	2012	В	2.3±0.05	1.55±0.05	8±0.1	3.5±0.05	1.75±0.05	4±0.1	2±0.05	4±0.1	1.55±0.03
CS3216	CC1206	3216	Е	3.5±0.1	1.88±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS3216	CC1206	3216	I	3.45±0.1	1.75±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS3216	CC1206	3216	I	3.7±0.1	1.85±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS3225	CC1210	3225	L	3.58±0.1	2.75±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS3225	CC1210	3225	J	3.58±0.1	2.85±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS3225	CC1210	3225	L	3.5±0.1	2.7±0.1	8±0.1	3.5±0.05	1.75±0.1	4±0.1	2±0.05	4±0.05	1.5±0.1
CS4532	CC1812	4532	М	4.9±0.1	3.6±0.1	12±0.1	5.5±0.05	1.75±0.1	8±0.1	2±0.05	4±0.05	1.5±0.1



# 2. Measurement Method



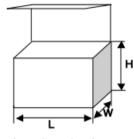
# Packing

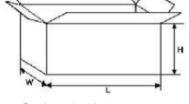
# (7) Packing Label(\* Reference image)



- ① Customer
- 2 Part No.3 Lot No
- ④ Q/ty

# (8) Packing Box





Inner box drawing

Out box drawing

# Packing Box Dimensions

(Unit : mm)

	Division	Size			
	Division	L	W	Н	
	7 " Reel Box (in 5 reels)	183	65	185	
Inner Box	7 " Reel Box (in 10 reels)	185	135	185	
	13 " Reel Box	330	65	337	
Out Box	7 " Reel Box	430	390	210	
Out box	13 " Reel Box	350	350	360	

### Caution

### ▶ Storage Condition

When solderability is considered, capacitor are recommended to be used in 12 months.

MLCC should be stored at 5~40 °C with a relative humidity of 20~70%

High humidity can reduce solderability due to oxidation.

Use the product within 6 months of the outgoing delivery date, and check the packaging if more than 6 months have passed.

It's recommended to use within 1 year to avoid solderability issues from long-term storage.

If over 1 year, verify solderability before use.

### ▶ The Regulation of Environmental Pollution Materials

Never use materials mentioned below in MLCC products regulated this document.

Pb, Cd, Hg, Cr+6, PBB(Polybrominated biphenyl), PBDE(Polybrominated diphenyl ethers), asbestos

### ▶ Reflow Soldering

- 1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.
- 2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference ( $\triangle$ T) within the range recommended in Table 1.

Table 1

Size code (EIA Code)	Temperature Difference	
0603, 1005, 1608, 2012, 3216	∆T≤150°C	
3225 size and over	∆T≤130°C	

### **Recommended Conditions**

Size code (EIA Code)	Lead Free Solder	
Peak Temperature	240 - 260°C	
Atmosphere	Air or N <sub>2</sub>	

<sup>\*</sup> Compliant Standard JESD22

### ► Standard condition for reflow soldering Temp(°C Peak Temp. (240~260) Liquidous Gradual Temp.(220) Cooling Δ Preheat Temp.(Max 200) Temp.(Min 150) Preheating Time 60~120sec 30~60sec

### ▶ Flow Soldering

- 1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.
- 2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference ( $\triangle$ T) within the range recommended in Table 2.

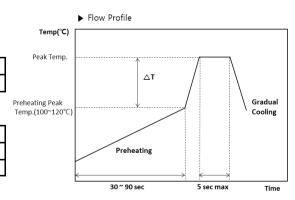
Table 2

<u>- 400.0 E</u>	
Size code	Temperature Difference
1608. 2012. 3216	∧T≤150°C

### Recommended Conditions

Conditions	Lead Free Solder	
Soldering Peak Temperature	250 - 260°C	
Atmosphere	Air or N <sub>2</sub>	

\*Lead Free Solder : Sn-3.0Ag-0.5Cu



# Notice

### ▶ Land Dimension

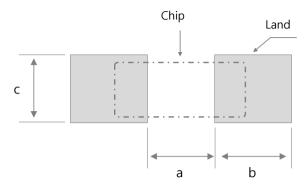


Table . Reflow Soldering Method

Chip size	Chip tol. a		b	с
[mm]	[mm]	[mm]	[mm]	[mm]
0603	±0.03	0.2~0.25	0.2~0.3	0.25~0.35
0603	±0.05/±0.09	0.23~0.3	0.25~0.35	0.3~0.4
1005	±0.1	0.3~0.5	0.35~0.45	0.4~0.6
1005	±0.2	0.4~0.6	0.4~0.5	0.5~0.7
1608	±0.1	0.6~0.8	0.6~0.7	0.6~0.8
1606	±0.2	0.7~0.9	0.7~0.8	0.8~1.0
2012	±0.1	0.9~1.3	0.6~0.8	1.2~1.4
2012	±0.2	1.0~1.4	0.6~0.8	1.2~1.4
3216	±0.2	1.8~2.0	0.9~1.2	1.5~1.7
3210	±0.3	1.9~2.1	1.0~1.3	1.7~1.9
3225		2.0~2.4	1.0~1.2	1.8~2.3
4532		3.0~3.5	1.2~1.4	2.3~3.0
5750		4.0~4.6	1.4~1.6	3.5~4.8

<sup>\*</sup>Please confirm the suitable land dimensions, which are determined through the evaluation of the actual SET and PCB

### Note

### (1) 'Aging'/'De-aging' behavior of high dielectric constant type MLCCs

(Typically represented by X7R temperature characteristic of which main composition is BaTiO<sub>3</sub>)

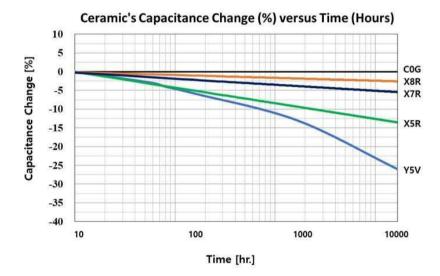
'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric ceramic capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

 $Ct = C_{24} (1 - k \log 10 t)$ 

where,

Ct : Capacitance value, t hours after the start of 'aging  $C_{24}$ : Capacitance value, 24 hours after its manufacture k : Aging constant (capacitance decrease per decade-hour)

t: time, in hours, from the start of 'aging'



The capacitance value can be restored (also known as 'de-aged') by exposing the component to elevated temperatures approaching its curie temperature (approximately 120°C). This 'de-aging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing, or by baking at 150°C for about 1 hour.

### (2) Caution of Application

Please contact our sales representatives or product engineers before using the products in this catalog for the applications listed below, which require especially high reliability for the prevention of defects which might directly damage a third party's life, body or property, or when one of our products is intended for use in applications other than those specified in this catalog.

- a Aircraft equipment
   b Aerospace equipment
   c Undersea equipment
   d Power plant equipment
   m Medical equipment
   f Transportation equipment (vehicles, trains, ships, etc.)
- Medical equipment
   Transportation equipment (venicles, trains, snips, etc.)
   Traffic signal equipment
   Disaster prevention / crime prevention equipment
- i) Industrial equipment (Conveyors, Robot equipment, etc)i) Led equipment
- Application of similar complexity and/or reliability requirements to the applications listed above